

L Number	Hits	Search Text	DB	Time stamp
1	2124099	(integrated adj circuit) ic semiconductor die chip dice	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:07
2	579735	flipchip (flip adj chip) bumps balls standoff	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:08
3	1575	257/686	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:08
4	0	257/6856	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:08
5	734	257/685	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:08
6	2481	257/723	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:08
7	1398	257/777	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:08
8	2304	257/778	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:08
9	1931	257/737	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:08
10	1543	257/738	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:08
11	1641	257/784	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:08
12	1783	257/786	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:08
13	2602195	((integrated adj circuit) ic semiconductor die chip dice) (flipchip (flip adj chip) bumps balls standoff)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:09

14	8954	257/686 257/685 257/723 257/777 257/778 257/737 257/738 257/784 257/786	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:09
15	124853	438/\$7.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:09
16	91119	361/\$7.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:09
17	4715	(flipchip (flip adj chip) bumps balls standoff) and (257/686 257/685 257/723 257/777 257/778 257/737 257/738 257/784 257/786)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/28 11:14

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